

Title (en)

Preparing substrates containing polymers for metallization

Title (de)

Herstellung von Substraten mit Polymeren zur Metallisierung

Title (fr)

Préparation de substrats contenant des polymères pour la métallisation

Publication

EP 2287357 B1 20160413 (EN)

Application

EP 10173029 A 20100817

Priority

US 27450509 P 20090818

Abstract (en)

[origin: EP2287357A2] Methods of swelling and topographically altering polymers of substrates using low foaming compositions are disclosed. Solvent swells which are stable, homogeneous and low foaming are applied to substrates containing polymers to swell and soften the polymers followed by applying an oxidizer to topographically alter and desmear the polymers in preparation for metallization of the substrate.

IPC 8 full level

C08J 7/02 (2006.01); **C23C 18/04** (2006.01); **C23C 18/16** (2006.01); **C23C 18/20** (2006.01); **C23C 18/30** (2006.01); **C23C 18/24** (2006.01); **C23C 18/28** (2006.01); **C23C 18/40** (2006.01)

CPC (source: EP KR US)

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